

<b>Notice of References Cited</b>		Application/Control No.	Applicant(s)/Patent Under Reexamination	
		10/767,658	OKAMOTO ET AL.	
Examiner		Art Unit		Page 1 of 1
SHAMBHAVI PATEL		2128		

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
	B	US-			
	C	US-			
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

**FOREIGN PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
*	U	Sarvar et al. 'Effective Modeling of the Reflow Soldering Process: Bases, Construction, and Operation of a Process Model'. IEEE Transactions on Component, Packaging, and Manufacturing Technology--Part C, Vol. 21, No. 2. April, 1998.
	V	Yang, et al. "Modeling and Implementation of a Neurofuzzy System for Surface Mount Assembly Defect Prediction and Control", IIE Transactions, 2002.
	W	
	X	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.